

PATENT ASSIGNMENT COVER SHEET

Electronic Version v1.1
 Stylesheet Version v1.2

EPAS ID: PAT2864453

SUBMISSION TYPE:	NEW ASSIGNMENT
NATURE OF CONVEYANCE:	ASSIGNMENT
CONVEYING PARTY DATA	
Name	Execution Date
JI-YUN KWON	05/16/2014
JIN-HEE KANG	05/16/2014
DAE-YUN KIM	05/16/2014
SANG-KYEON KIM	05/16/2014
SANG-SOO KIM	05/16/2014
YONG-TAE KIM	05/16/2014
KUN-BAE NOH	05/16/2014
EUN-BI PARK	05/16/2014
JAE-YEOL BAEK	05/16/2014
JAE-HWAN SONG	05/16/2014
EUN-KYOUNG YOUN	05/16/2014
BUM-JIN LEE	05/16/2014
JONG-HWA LEE	05/16/2014
JIN-YOUNG LEE	05/16/2014
CHUNG-BEUM HONG	05/16/2014
EUN-HA HWANG	05/16/2014
IN-CHUL HWANG	05/16/2014
RECEIVING PARTY DATA	
Name:	CHEIL INDUSTRIES INC.
Street Address:	58 GUMI-DAERO
Internal Address:	GUMI-SI, GYEONGSANGBUK-DO
City:	GUMI-SI
State/Country:	KOREA, REPUBLIC OF
Postal Code:	730-710
PROPERTY NUMBERS Total: 1	
Property Type	Number
Application Number:	14283342
CORRESPONDENCE DATA	
Fax Number:	(704)945-6735
PATENT	

Correspondence will be sent to the e-mail address first; if that is unsuccessful, it will be sent using a fax number, if provided; if that is unsuccessful, it will be sent via US Mail.

Phone: 704-945-6700
Email: docket@ahpapatent.com
Correspondent Name: MELISSA B. PENDLETON
Address Line 1: 11610 N. COMMUNITY HOUSE ROAD
Address Line 2: SUITE 200
Address Line 4: CHARLOTTE, NORTH CAROLINA 28277

ATTORNEY DOCKET NUMBER:	7020.174
NAME OF SUBMITTER:	MELISSA B. PENDLETON
SIGNATURE:	/Melissa B. Pendleton/
DATE SIGNED:	05/21/2014

Total Attachments: 6

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RECORDATION FORM COVER SHEET
PATENTS ONLY

To the Director of the U.S. Patent and Trademark Office: Please record the attached documents or the new address(es) below.

1. Name of conveying party(ies)

- | | | |
|-------------------|---------------------|---------------------|
| 1) JI-YUN KWON | 8) EUN-BI PARK | 15) CHUNG-BEUM HONG |
| 2) JIN-HEE KANG | 9) JAE-YEOL BAEK | 16) EUN-HA HWANG |
| 3) DAE-YUN KIM | 10) JAE-HWAN SONG | 17) IN-CHUL HWANG |
| 4) SANG-KYEON KIM | 11) EUN-KYOUNG YOUN | |
| 5) SANG-SOO KIM | 12) BUM-JIN LEE | |
| 6) YONG-TAE KIM | 13) JONG HWA LEE | |
| 7) KUN-BAE NOH | 14) JIN-YOUNG LEE | |

Additional name(s) of conveying party(ies) attached? ☐ Yes ☒ No

2. Name and address of receiving party(ies)

Name: Cheil Industries Inc.

Internal Address: _____

Street Address: 58 Gumi-daero

City: Gumi-si

State: Gyeongsangbuk-do

Country: South Korea Zip: 730-710

Additional name(s) & address(es) attached? ☐ Yes ☒ No

3. Nature of conveyance/Execution Date(s):

Execution Date(s) May 16, 2014

- | | |
|---|---|
| <input checked="" type="checkbox"/> Assignment | <input type="checkbox"/> Merger |
| <input type="checkbox"/> Security Agreement | <input type="checkbox"/> Change of Name |
| <input type="checkbox"/> Joint Research Agreement | |
| <input type="checkbox"/> Government Interest Assignment | |
| <input type="checkbox"/> Executive Order 9424, Confirmatory License | |
| <input type="checkbox"/> Other _____ | |

4. Application or patent number(s):

☐ This document is being filed together with a new application.

A. Patent Application No.(s)

14/283,342

B. Patent No.(s)

Additional numbers attached? ☐ Yes ☒ No

5. Name and address to whom correspondence concerning document should be mailed:

Name: Additon, Higgins, Pendleton & Ashe, P.A.

Internal Address: _____

Street Address: 11610 N. Community House
Road, Suite 200

City: Charlotte

State: NC Zip: 28277-2199

Phone Number: 704-945-6700

Fax Number: 704-945-6735

Email Address: _____

6. Total number of applications and patents involved: 1

7. Total fee (37 CFR 1.21(h) & 3.41) \$ 40.00

- ☒ Authorized to be charged by credit card
☐ Authorized to be charged to deposit account
☐ Enclosed
☐ None required (government interest not affecting title)

8. Payment Information

a. Credit Card Last 4 Numbers _____
Expiration Date _____

b. Deposit Account Number _____

Authorized User Name _____

9. Signature: /Melissa B. Pendleton/

May 21, 2014

Melissa B. Pendleton

Signature

Date

Name of Person Signing

Total number of pages including cover sheet, attachments, and documents: 6

ASSIGNMENT

WHEREAS, I, **Ji-Yun KWON**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jin-Hee KANG**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Dae-Yun KIM**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Sang-Kyeon KIM**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Sang-Soo KIM**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Yong-Tae KIM**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Kun-Bae NOH**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Eun-Bi PARK**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jae-Yeol BAEK**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jae-Hwan SONG**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Eun-Kyoung YOUN**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Bum-Jin LEE**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jong-Hwa LEE**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Jin-Young LEE**, a Korean citizen, with a mailing address of Cheil Industries

Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Chung-Beum HONG**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; **Eun-Ha HWANG**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea; and **In-Chul HWANG**, a Korean citizen, with a mailing address of Cheil Industries Inc., 56 Gosan-ro, Uiwang-si, Gyeonggi-do, Republic of Korea (hereinafter referred to as "ASSIGNOR"), am a joint inventor of certain new and useful improvements (hereinafter collectively referred to as "INVENTION") in *Positive Photosensitive Resin Composition, and Photosensitive Resin Film and Display Device Prepared by Using the Same*, for which an application for United States Letters Patent is being filed concurrently herewith and which application claims priority from a Korean application filed on August 13, 2013, under Serial No. 10-2013-0096165, all applications listed above being hereinafter referred to as the "APPLICATION"; and

WHEREAS, Cheil Industries Inc., a Korean corporation (hereinafter referred to as "ASSIGNEE"), having a principal place of business at 58 Gumi-daero, Gumi-si, Gyeongsangbuk-do 730-710, Republic of Korea, has acquired the equitable right, title, and interest—and is desirous of acquiring any remaining right, title, and interest—in and to said INVENTION as described in said APPLICATION, and in and to any and all Letters Patent that shall be granted with respect to said INVENTION in the United States of America and all foreign countries;

NOW, THEREFORE, be it known that for good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, I, the ASSIGNOR, have sold, assigned, transferred, and conveyed unto said ASSIGNEE, its successors and assigns, my equitable right, title, and interest—and by these presents do hereby sell, assign, transfer, and convey unto said ASSIGNEE, its

successors and assigns any remaining right, title, and interest—in and to said INVENTION and APPLICATION, in and to any and all continuations, continuations-in-part, or divisions thereof, and in and to any and all Letters Patent of the United States of America and all foreign countries or reissues, reexaminations, or extensions thereof that may be granted therefore or thereon, for the full term for which said Letters Patent may be granted, together with the right to claim the priority of said APPLICATION in all foreign countries in accordance with international treaties and conventions, the same to be held and enjoyed by said ASSIGNEE, its successors and assigns, as fully and entirely as the same would have been held and enjoyed by me if an assignment and sale had not been made.

I acknowledge that at the time the INVENTION was made, the INVENTION was subject to an obligation of assignment to said ASSIGNEE. I further acknowledge that said ASSIGNEE has the sole right to determine patent prosecution strategies with respect to said INVENTION and all corresponding applications, and hereby request that Letters Patent be issued in accordance with this assignment.

I further covenant and agree to bind my heirs, legal representatives, and assigns, promptly to communicate to said ASSIGNEE or its representatives any facts known to me relating to said INVENTION, to testify in any interference or legal proceedings involving said INVENTION, to execute any additional papers that may be requested to confirm the right of the ASSIGNEE, its representatives, successors or assigns to secure patent or similar protection for said INVENTION in all countries and to vest in the ASSIGNEE complete title to said INVENTION and Letters Patent, without further compensation, but at the expense of said ASSIGNEE, its successors, assigns and other legal representatives.

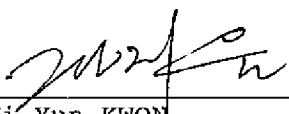
As the below named inventor, I hereby declare:

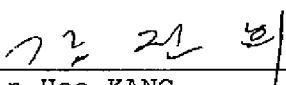
The application for United States Letters Patent being filed concurrently herewith was made or authorized to be made by me.

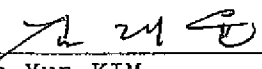
I believe that I am the original or an original joint inventor of a claimed invention in the application.

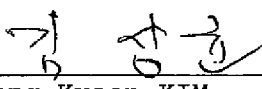
I hereby acknowledge that any willful false statement made in the declaration is punishable under 18 U.S.C. 1001 by fine or imprisonment of not more than five (5) years, or both.

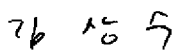
IN WITNESS WHEREOF, I have hereunto signed my name on the day and year set forth below.

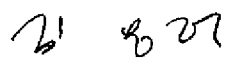
_____, May 16, 2014 
Ji-Yun KWON

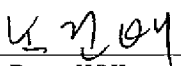
_____, May 16, 2014 
Jin-Hee KANG


_____, May 16, 2014 
Dae-Yun KIM

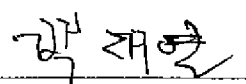
_____, May 16, 2014 
Sang-Kyeon KIM

_____, May 16, 2014 
Sang-Soo KIM

_____, May 16, 2014 
Yong-Tae KIM

_____, May 16, 2014 
Kun-Bae NOH

_____, May 16, 2014 
Eun-Bi PARK

_____, May 16, 2014 

Jae-Yeol BAEK

May 16, 2014

송재환

Jae-Hwan SONG

May 16, 2014

윤은경

Eun-Kyoung YOUN

May 16, 2014

이범진

Bum-Jin LEE

May 16, 2014

Lee Jong Hwa

Jong-Hwa LEE

May 16, 2014

이정영

Jin-Young LEE

May 16, 2014

홍종범

Chung-Beum HONG

May 16, 2014

황은하

Eun-Ha HWANG

May 16, 2014

황인철

In-Chul HWANG